FY2026 1Q (Fiscal Year Ending March 31, 2027) Financial Results Presentation Materials

August 6, 2026

JX Advanced Metals

Table of Contents

1 Highlights

2 FY2026 1Q (Fiscal year ending March 31, 2027) Results

3 FY2026 (Fiscal year ending March 31, 2027) Forecasts

4 Appendix

Highlights

Highlights – FY2026 1Q Results and FY2026 Forecasts

Operating Profit

FY2026 1Q

Same period in FY2025	Results	Difference
29.6 bil. Yen	**81.4 bil. Yen**	**+51.8 bil. Yen**
Exchange rate 145 JPY/USD	Exchange rate 159 JPY/USD	Exchange rate 14 JPY/USD weak yen
Copper(LME) 432 ¢/lb	Copper(LME) 604 ¢/lb	Copper(LME) +172 ¢/lb

External Environment & One-off Factors

- Market Environment ＋26.5 bil. Yen
- One-off factors ＋19.0 bil. Yen
(Gain from partial sale of Caserones interest)

Business Factors

- Increased sales in Focus Businesses ＋8.0 bil. Yen

FY2026 Full-year Forecast

Forecasts in May	Forecasts in August	Difference
190.0 bil. Yen	**232.0 bil. Yen**	**+42.0 bil. Yen**
Exchange rate 150 JPY/USD	Exchange rate 157 JPY/USD	Exchange rate 7 JPY/USD weak yen
Copper(LME) 520 ¢/lb	Copper(LME) 586 ¢/lb	Copper(LME) +66 ¢/lb

External Environment

- Market Environment ＋40.0 bil. Yen
- Reduced mine production due to adverse weather conditions in Chile -6.0 bil. Yen

Business Factors

- Increased sales in Focus Businesses ＋3.0 bil Yen
- Improved selling prices of Focus Businesses ＋2.5 bil. Yen

Performance Trend

		FY2023 Results	FY 2024 Results	FY2025 Results	FY 2026 Forecasts
Operating Profit	Consolidated	86.2 bil Yen	112.5 bil. Yen	175.0 bil. Yen	**232.0 bil. Yen**
	Focus Businesses	27.3 bil. Yen	51.8 bil. Yen	71.0 bil. Yen	**100.0 bil. Yen**
Operating Profit margin	Focus Businesses	9%	13%	14%	**17%**

Expecting steady growth in both overall business performance and Focus Businesses

Highlights – Sales volume Growth rate

			FY2026 1Q Results (FY2025 1Q ▶FY2026 1Q)		FY2026 Full-year Forecasts (FY2025 Results ▶ FY2026 Forecasts) in May		in August	
Semiconductor Materials	Thin Film Materials	Sputtering targets for SEMI	+26%	Continued solid performance, supported by expanding demand for AI data center applications	+19%	⇗	+21%	Progressing steadily Forecasts for sputtering targets for SEMI and magnetic devices have been revised upward For InP substrates, initiatives to improve production efficiency at existing facilities are ongoing
		Sputtering targets for magnetic devices	+8%		+7%	⇗	+8%	
		InP substrates	+8%		+13%	⇨	+13%	
	TaNb*	Tantalum Powder for tantalum capacitor	+89%		+16% For AI Datacenter +62% Others +9%	⇘	+2% For AI Datacenter +62% Others ▲9%	AI data center-related demand remains strong. Seeking to improve profitability through selling price improvements and a portfolio shift toward higher-margin products
ICT Materials	Functional Materials	Rolled Annealed Copper Foil	+3%	Sales exceeded the high level achieved in the same period of the previous fiscal year	+5%	⇨	+5%	Progressing steadily Forecast for copper titanium alloys has been revised upward
		Copper Titanium Alloys	+42%	Continued solid performance, supported by expanding demand for AI data center applications	+32%	⇗	+33%	

*TaNb: Tantalum and Niobium

JX Advanced Metals

Highlights – Capacity increase

Semiconductor Materials

✓ Driving capacity expansion to capture growth in AI data centers

		Location	Expansion scale (Based on Production capacity)	Start of operations
	**Sputtering targets for SEMI**	**Japan (Hitachinaka works)**	(vs. FY2025) **1.3x** To support the anticipated growth, expanding local finishing and processing capacity Taiwan: **1.4x** Korea: **2.0x**	FY2027 onward
	**Sputtering targets for magnetic devices**	**Japan (Isohara works)**	(vs. FY2025) **1.2x**	2H FY2026
	**InP substrates**	**Japan (Isohara/Hitachinaka works)**	(vs. FY2025) **7-10x**	From 2H FY2026 onward
	**Tantalum Powder**	**Thailand**	(vs. FY2025) **1.5x**	From 1H CY2027 onward

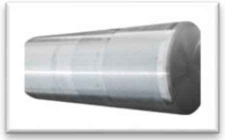
➢ Consider further capacity expansions as necessary for products expected to experience rapid demand growth, such as copper titanium alloys

Highlights – Toho Titanium

ICT Materials

TOHO TITANIUM CO.,LTD.

✓ Wholly-owned subsidiary since June 2026 (share exchange)

Main business	Main products	Main applications	Current Status / Future Direction
Titanium Business	Titanium Sponge 	Aircraft engine components and airframe materials	Expanding aerospace applications for both companies' products through the sharing of sales channels and market intelligence. Evaluating the optimal business structure to support future growth
	High-Purity Titanium 	Sputtering targets for SEMI	Strengthening the supply of high-purity titanium for sputtering targets for SEMI applications
Chemicals Business	Ultra-fine Nickel Powder 	Multi-layer Ceramic Capacitors (MLCCs)	In response to strong demand, reviewing measures to expand production capacity and strengthen manufacturing capabilities. Accelerating marketing and product development through market intelligence sharing with JX Advanced Metals <u>to capture demand from AI data center</u>
Catalysts Business	THC Catalysts 	Polypropylene and polyolefins for automotive interior and exterior components and home appliances	Enhancing market analysis and customer development activities to expand sales by leveraging JX Advanced Metals' network
New Materials Division	CVD/ALD precursor materials 	Semiconductor thin-film deposition materials	Reviewing capacity expansion initiatives in anticipation of future demand growth and broadening the precursor product lineup

AI Server MLCC Market Growth

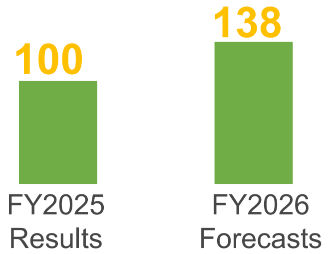
20-40%

(CAGR 2025~2035)

*Our estimate

Ultra-Fine Nickel Powder Sales Volume

(Index: FY2025 = 100)



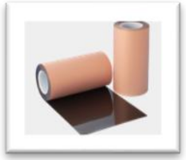
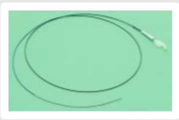
Strong growth expected, driven by expanding demand for our products and continued growth in the MLCC market. The capacity expansion previously announced in February 2023 has already started operation in FY2026. Sales expansion through enhanced marketing activities and further capacity expansion are under evaluation

Highlights – TATSUTA Electric Wire and Cable

ICT Materials

TATSUTA

✓ Wholly-owned subsidiary since November 2024 (tender offer and share consolidation)

Main business	Main products		Main applications	Current Status / Future Direction
Electric wires & cables	Electric wires and cables for infrastructure and industrial equipment		Electric wires and cables for infrastructure applications (power plants, power distribution facilities, and building construction and sales) and industrial equipment applications (factory automation systems, robots, and machine tools)	Achieved revenue growth through the execution of pricing strategies. Promoting raw material source diversification, increased procurement of recycled materials, and product differentiation through the utilization of recycled copper
Electronic materials	EMI shielding films		EMI shielding films designed to prevent malfunctions in electronic devices such as smartphones caused by electromagnetic noise	Building cross-channel opportunities through the sharing of smartphone market intelligence, while accelerating performance improvements of existing products and the development of new products
Sensors & Medical Products	Liquid leakage detection sensor		Liquid leakage detection sensor for AI servers and data centers	Rapid demand growth led to the decision to expand capacity. Further capacity expansion and the utilization of JX Advanced Metals' sites and sales channels are under consideration
	Materials and products for medical devices		Microcatheters, carbon lead wires for ECG electrodes etc.	Promoting collaboration in product development and other areas

AI Server Shipment Growth Rate

29.6%

(CAGR 2025~2030)

(Source) Prismark Partners LLC

In response to growing AI server-related demand, we decided to increase production capacity by approx. 30% vs. FY2025 (announced in August 2026). Considering additional capacity expansion with anticipating further demand growth

FY2026 1Q (Fiscal year ending March 31, 2027) Results

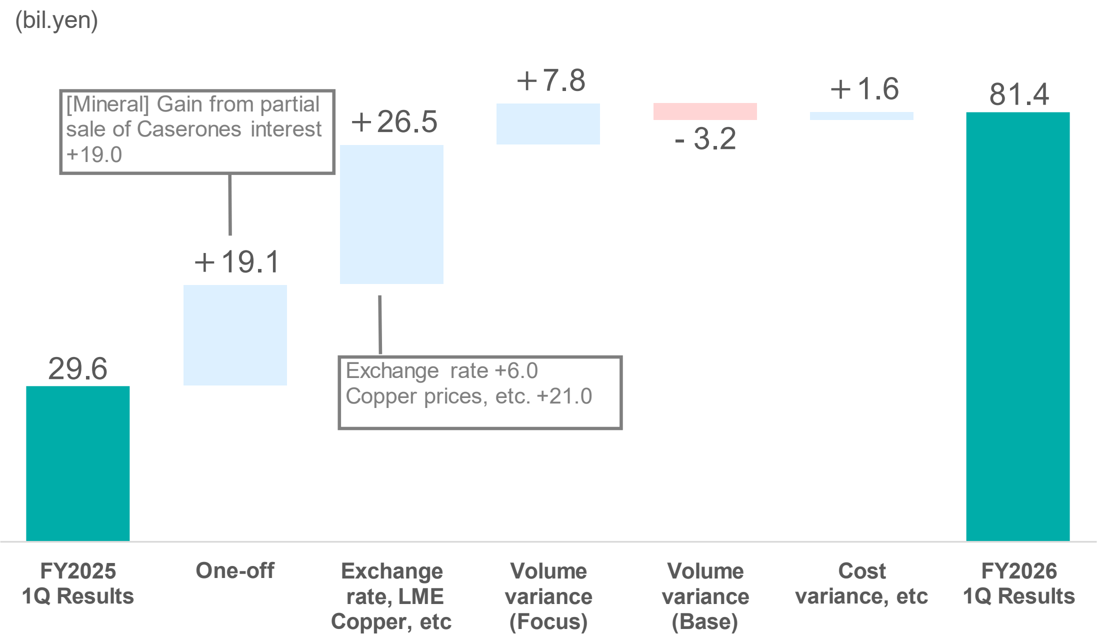
Consolidated statement of income

bil. yen		FY2025 1Q Results	FY2026 1Q Results	Difference Absolute	 %
Revenue		**191.3**	**260.6**	**＋69.3**	**＋36%**
(Focus Businesses)		117.0	145.2	＋28.2	＋24%
(Base Businesses)		75.0	123.7	＋48.7	＋65%
(Other)		-0.7	-8.3	- 7.6	―
Operating profit		**29.6**	**81.4**	**＋51.8**	**＋175%**
(Focus Businesses)		16.2	27.5	＋11.3	＋70%
(Base Businesses)		14.6	56.8	＋42.2	＋289%
(Other)		-1.2	-2.9	- 1.7	―
Profit before tax		**28.5**	**79.6**	**＋51.1**	**＋179%**
Net profit		**23.2**	**60.4**	**＋37.2**	**＋160%**
Profit attributable to owners of parent		**18.9**	**53.1**	**＋34.2**	**＋181%**
Exchange rate (JPY/USD)		145	159	＋14	＋10%
LME copper price (¢/lb)	Average	432	604	＋172	＋40%
	End/start of period	439/455	552/605		

Revenue and operating profit by business segment

		bil. yen	FY2025 1Q Results	FY2026 1Q Results	Difference Absolute	Difference %
Focus Businesses	Semiconductor materials	Revenue	38.8	52.1	＋13.3	＋34%
		OP	8.5	14.4	＋5.9	＋69%
	ICT materials	Revenue	78.2	93.1	＋14.9	＋19%
		OP	7.7	13.1	＋5.4	＋70%
Base Businesses	Metals & Recycling	Revenue	75.0	123.7	＋48.7	＋65%
		OP	14.6	56.8	＋42.2	＋289%
Other	Common expenses	Revenue	- 0.7	- 8.3	- 7.6	―
		OP	- 1.2	- 2.9	- 1.7	―
Total		**Revenue**	**191.3**	**260.6**	**＋69.3**	**＋36%**
		OP	**29.6**	**81.4**	**＋51.8**	**＋175%**

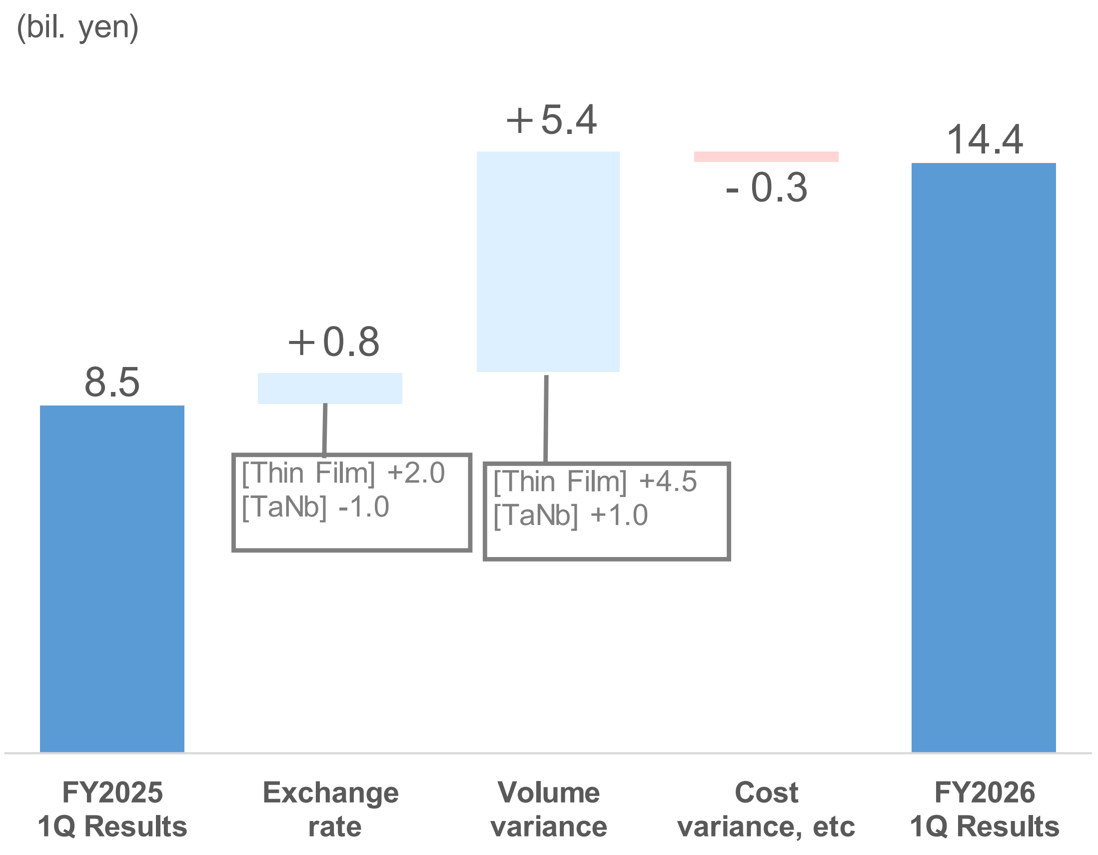
Difference in operating profit



(Details)	＋ 19.1	＋ 26.5	＋ 7.8	-3.2	＋ 1.6	For more details
SEMI	―	＋ 0.8	＋ 5.4	―	- 0.3	p12
ICT	―	＋ 1.9	＋ 2.4	―	＋ 1.1	p13
Base	＋ 19.1	＋ 23.8	―	- 3.2	＋ 2.5	p14
Others	―	―	―	―	- 1.7	

Analysis of difference in operating profit: Semiconductor Materials segment (FY2026 1Q Results vs. FY2025 1Q Results)

Analysis of difference in operating profit



Segment overview

Thin Film Materials	- OP increased due to growth in sales of main products driven by the continuous expansion of AI data center related demand
TaNb	- OP declined due to the appreciation of the euro etc., despite higher sales volumes of tantalum powder for capacitors

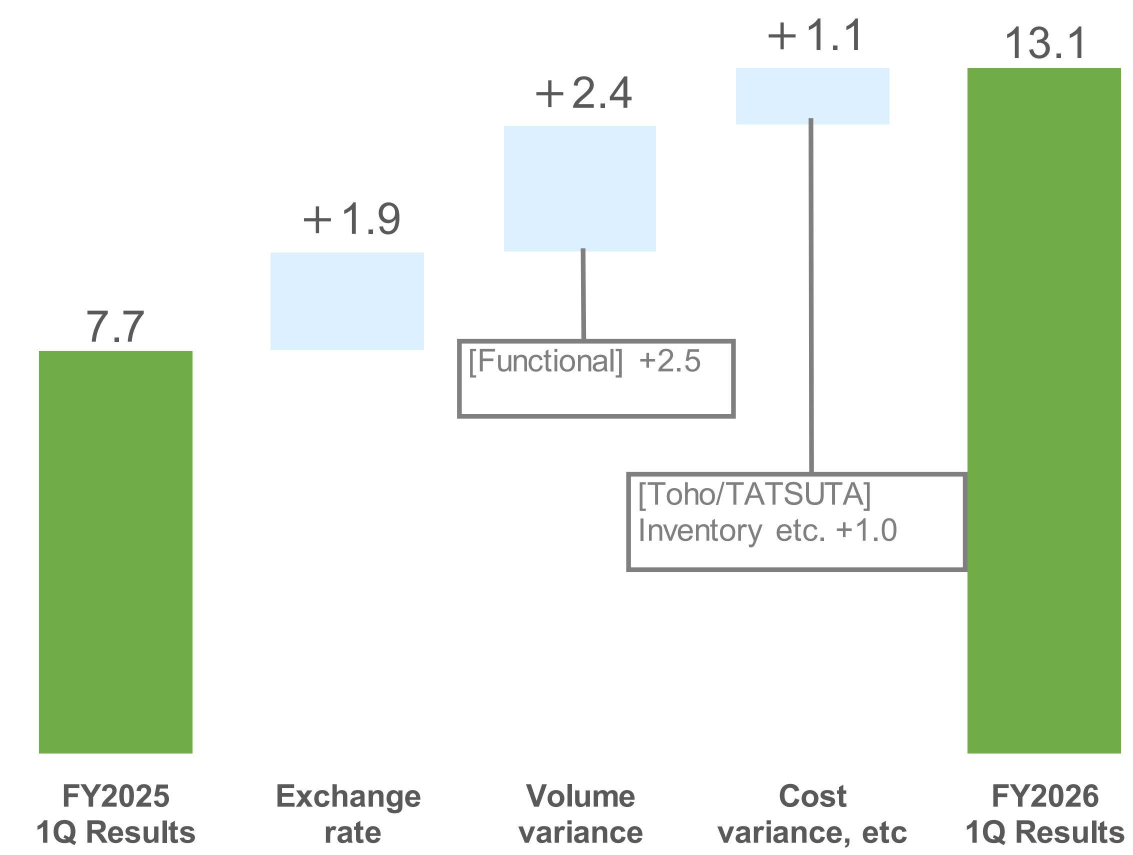
Revenue and operating profit by segment

	bil. yen	FY2025 1Q Results	FY2026 1Q Results	Difference Absolute	Difference %
Thin film materials	Revenue	32.5	45.6	+13.1	+40%
	OP	8.4	15.3	+6.9	+82%
Tantalum and Niobium	Revenue	10.0	10.8	+0.8	+8%
	OP	0.3	-1.1	- 1.4	-
Adjustments, etc.	Revenue	-3.7	-4.3	- 0.6	-
	OP	-0.2	0.2	+0.4	-
Segment total	**Revenue**	**38.8**	**52.1**	**+13.3**	**+34%**
	OP	**8.5**	**14.4**	**+5.9**	**+69%**

Analysis of difference in operating profit: ICT Materials segment (FY2026 1Q Results vs. FY2025 1Q Results)

Analysis of difference in operating profit

(bil. yen)



Segment overview

Functional Materials

- OP increased due to solid smartphone-related demand and increased sales resulting from expanding AI data center-related demand

Toho Titanium TATSUTA Electric Wire and Cable

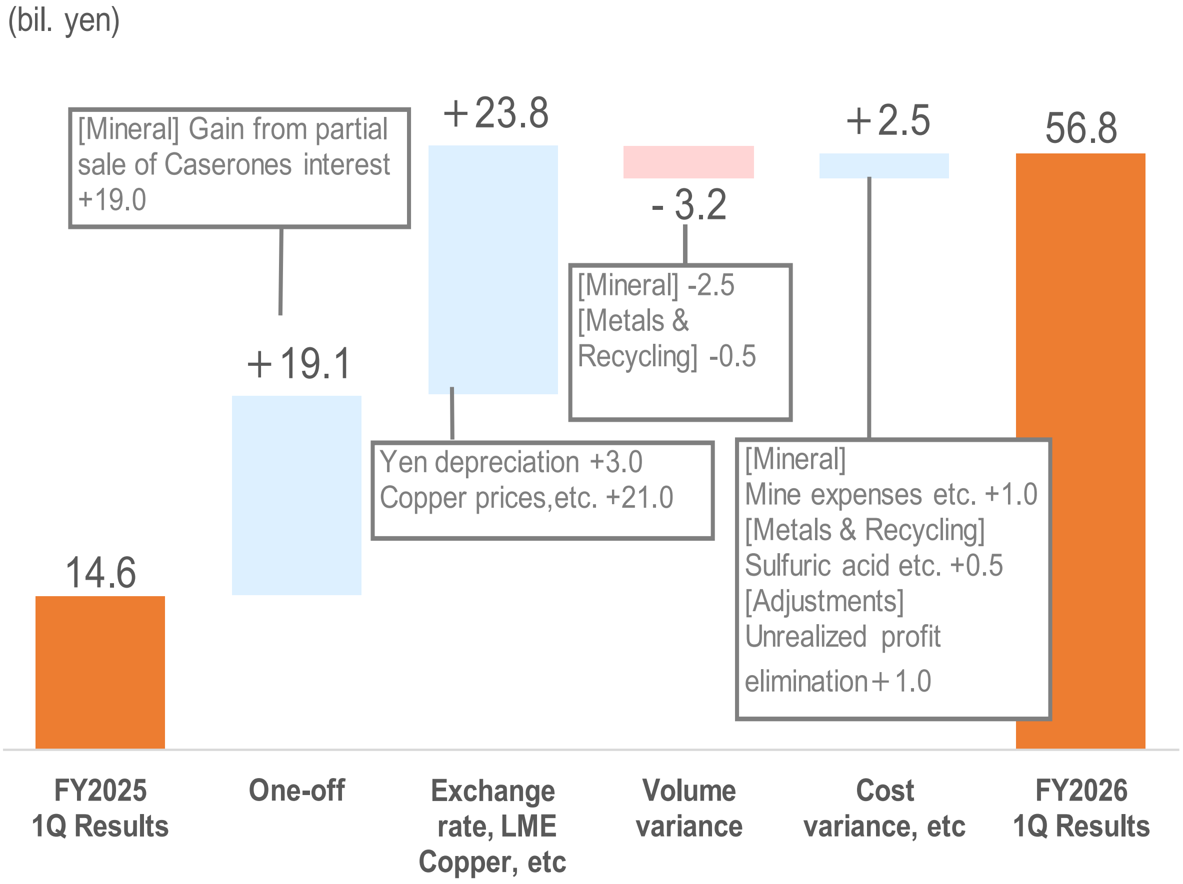
- OP increased mainly due to yen depreciation

Revenue and operating profit by segment

	bil. yen	FY2025 1Q Results	FY2026 1Q Results	Difference Absolute	Difference %
Functional materials	Revenue	37.8	49.3	+11.5	+30%
	OP	5.7	8.9	+3.2	+56%
Toho Titanium, TATSUTAElectric Wire and Cable, and etc.	Revenue	40.4	43.8	+3.4	+8%
	OP	2.0	4.2	+2.2	+110%
Segment total	**Revenue**	**78.2**	**93.1**	**+14.9**	**+19%**
	OP	**7.7**	**13.1**	**+5.4**	**+70%**

Analysis of difference in operating profit: Metals & Recycling segment (FY2026 1Q Results vs. FY2025 1Q Results)

Analysis of difference in operating profit



Segment overview

Mineral resources
- OP increased mainly due to gain from partial sale of Caserones interest, yen depreciation and higher copper prices etc.

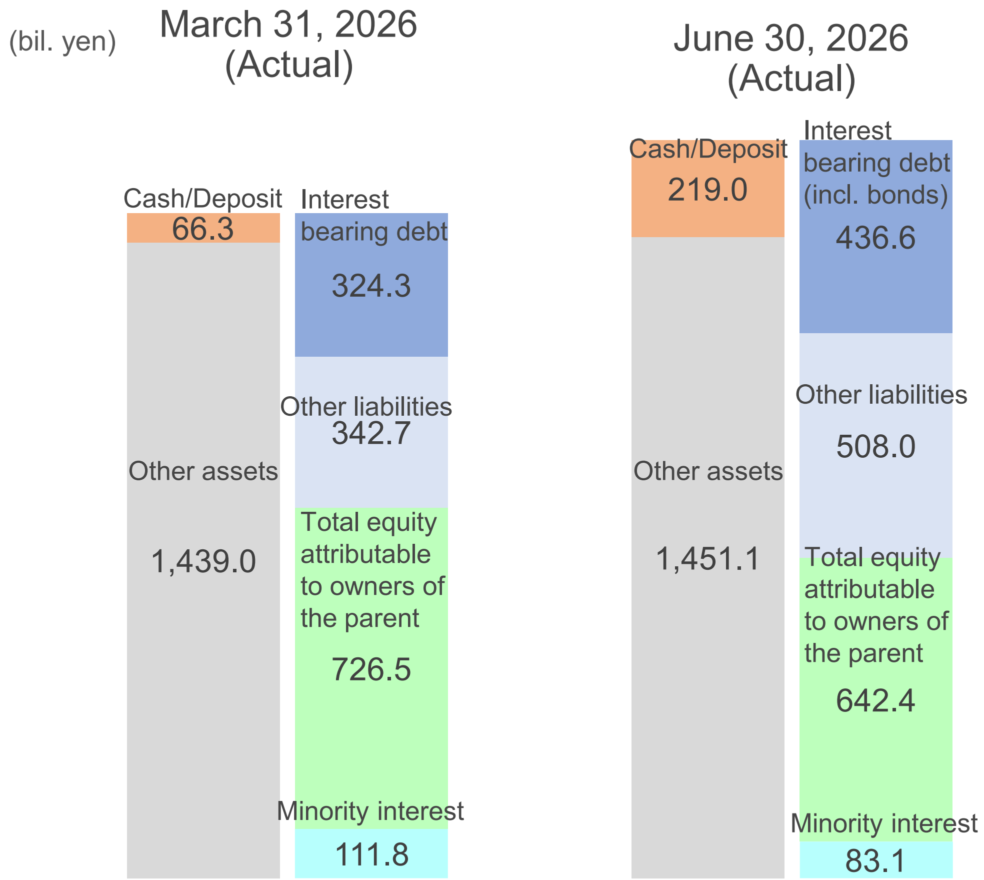
Metals & Recycling
- OP increased mainly due to yen depreciation and higher copper prices etc. and sulfuric acid margin

Revenue and operating profit by segment

	bil. Yen	FY2025 1Q Results	FY2026 1Q Results	Difference Absolute	Difference %
Mineral resources	Revenue	0.8	1.2	＋0.4	＋50%
	OP	11.5	47.2	＋35.7	＋310%
Metals & Recycling	Revenue	74.2	122.7	＋48.5	＋65%
	OP	3.5	9.1	＋5.6	＋160%
Adjustments, etc.	Revenue	0.0	-0.2	- 0.2	-
	OP	-0.4	0.5	＋0.9	-
Segment total	**Revenue**	**75.0**	**123.7**	**＋48.7**	**＋65%**
	OP	**14.6**	**56.8**	**＋42.2**	**＋289%**

Consolidated balance sheet・Cash flows / CAPEX, Depreciation, R&D expenses / Shareholder returns

Consolidated balance sheet



	March 31, 2026	June 30, 2026
Net interest-bearing debt	257.9	217.6

Net interest-bearing debt temporarily decreased, as the proceeds from the CB issuance intended for the tender remained as cash on hand at the end of this quarter

Consolidated cash flows

(bil. yen)	FY2026 1Q Results
Cash flows from operating activities	13.2
Cash flows from investing activities	7.9
Free Cash Flow	**21.1**
Cash flows from financing activities	130.9
Net increase (decrease)in cash and cash equivalents	**152.0**
Impact from exchange rate, etc.	0.7

CAPEX, Depreciation, R&D expenses

(bil. yen)	FY2024 Results	FY2025 Results	FY2026 1Q Results
CAPEX	92.3	84.5	25.6
Depreciation	44.0	44.7	12.6
R&D Expenses	17.8	20.0	5.3

FY2026 (Fiscal year ending March 31, 2027) Forecasts

Consolidated statement of income

bil. yen		FY2026 Forecasts (in May)	FY2026 Forecasts (in August)	Difference Absolute	%
Revenue		**930.0**	**1,025.0**	**+95.0**	**+10%**
(Focus Businesses)		530.0	585.0	+55.0	+10%
(Base Businesses)		420.0	470.0	+50.0	+12%
(Other)		-20.0	-30.0	- 10.0	-
Operating profit		**190.0**	**232.0**	**+42.0**	**+22%**
(Focus Businesses)		82.0	100.0	+18.0	+22%
(Base Businesses)		124.0	147.0	+23.0	+19%
(Other)		-16.0	-15.0	+1.0	-
Profit before tax		**178.0**	**221.0**	**+43.0**	**+24%**
Net profit		**140.0**	**174.0**	**+34.0**	**+24%**
Profit attributable to owners of parent		**114.0**	**141.0**	**+27.0**	**+24%**
Exchange rate (JPY/USD)		150	157	+7	+5%
LME copper price (¢/lb)	Average	520	586	+66	+13%
	End/start of period	552/520	552/580		

Exchange rate / LME copper price assumption

	July-September	October-March
Exchange rate (JPY/USD)	160	155
LME copper price (¢ /lb)	580	

Operating profit sensitivity (July 2026 onward)

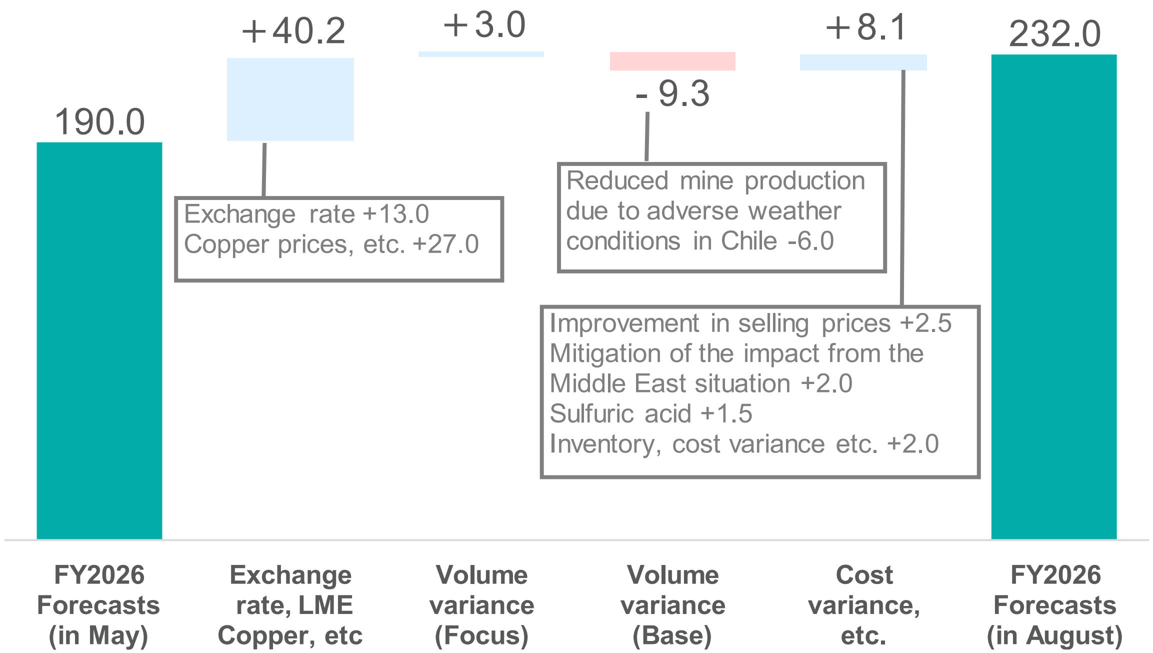
(bil. Yen)	Exchange rate 5-yen weaker yen	LME copper price +10¢/lb
Focus Businesses	+3.5	–
Base Businesses	+3.5	+3.5
Total	+7.0	+3.5

Revenue and operating profit by business segment

			bil. yen	FY2026 Forecasts (in May)	FY2026 Forecasts (in August)	Difference Absolute	Difference %
Focus Businesses		Semiconductor materials	Revenue	200.0	230.0	+30.0	+15%
			OP	50.0	61.0	+11.0	+22%
		ICT materials	Revenue	330.0	355.0	+25.0	+8%
			OP	32.0	39.0	+7.0	+22%
Base Businesses		Metals & Recycling	Revenue	420.0	470.0	+50.0	+12%
			OP	124.0	147.0	+23.0	+19%
Other		Common expenses	Revenue	- 20.0	- 30.0	- 10.0	-
			OP	- 16.0	- 15.0	+1.0	-
Total			**Revenue**	**930.0**	**1,025.0**	**+95.0**	**+10%**
			OP	**190.0**	**232.0**	**+42.0**	**+22%**

Difference in operating profit

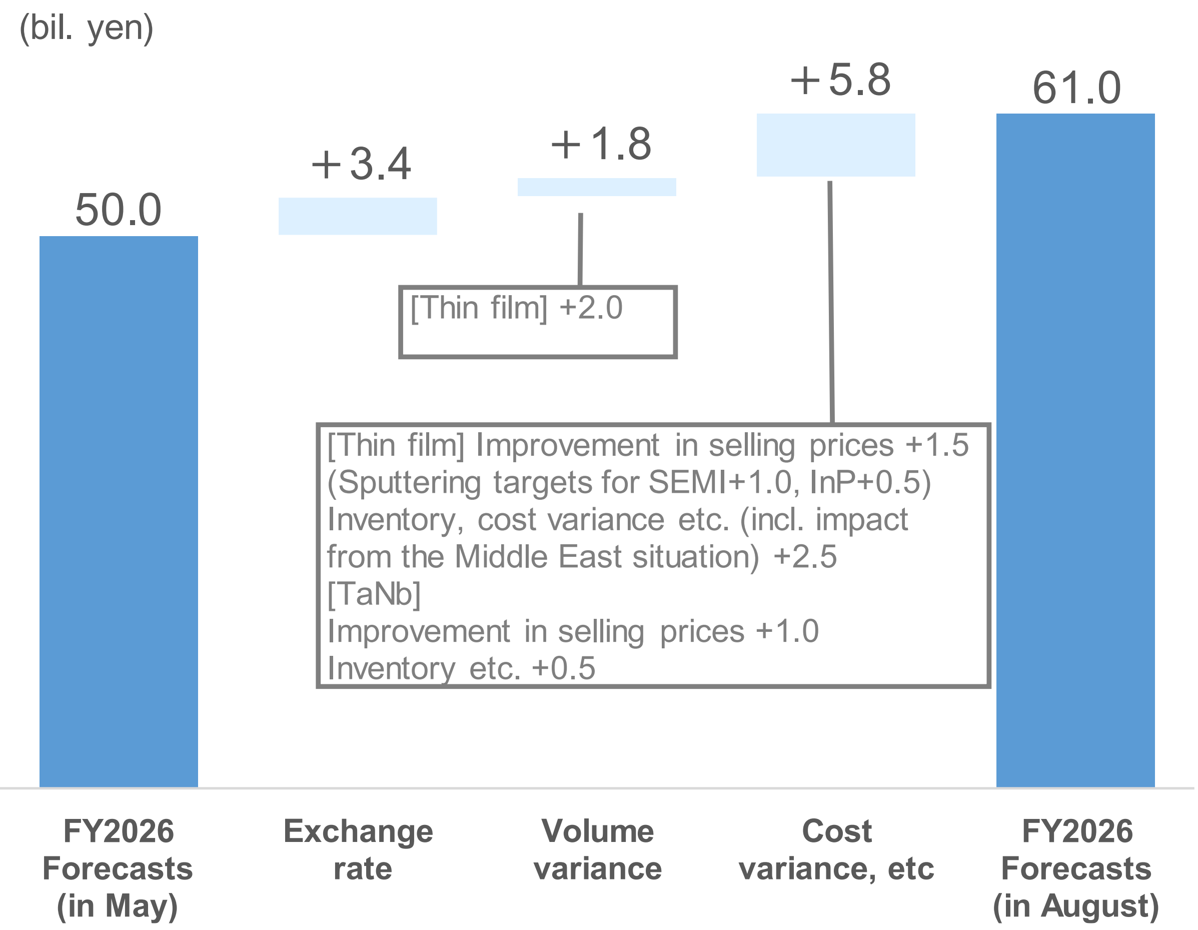
(bil.yen)



(Details)	+ 40.2	+ 3.0	- 9.3	+ 8.1	For more details
SEMI	+ 3.4	+ 1.8	—	+ 5.8	p19
ICT	+ 3.6	+ 1.2	—	+ 2.2	p20
Base	+ 33.2	—	- 9.3	- 0.9	p21
Others	—	—	—	+ 1.0	

Analysis of difference in operating profit: Semiconductor Materials segment (FY2026 Forecasts: August vs. May Forecasts)

Analysis of difference in operating profit



Segment overview

Thin Film Materials

- OP will increase mainly due to growth in sales volume, improved selling prices for sputtering targets for SEMI and InP substrates and yen depreciation

TaNb

- Despite the lower sales in low profitable tantalum powder for capacitors, OP will increase due to improved selling prices etc.

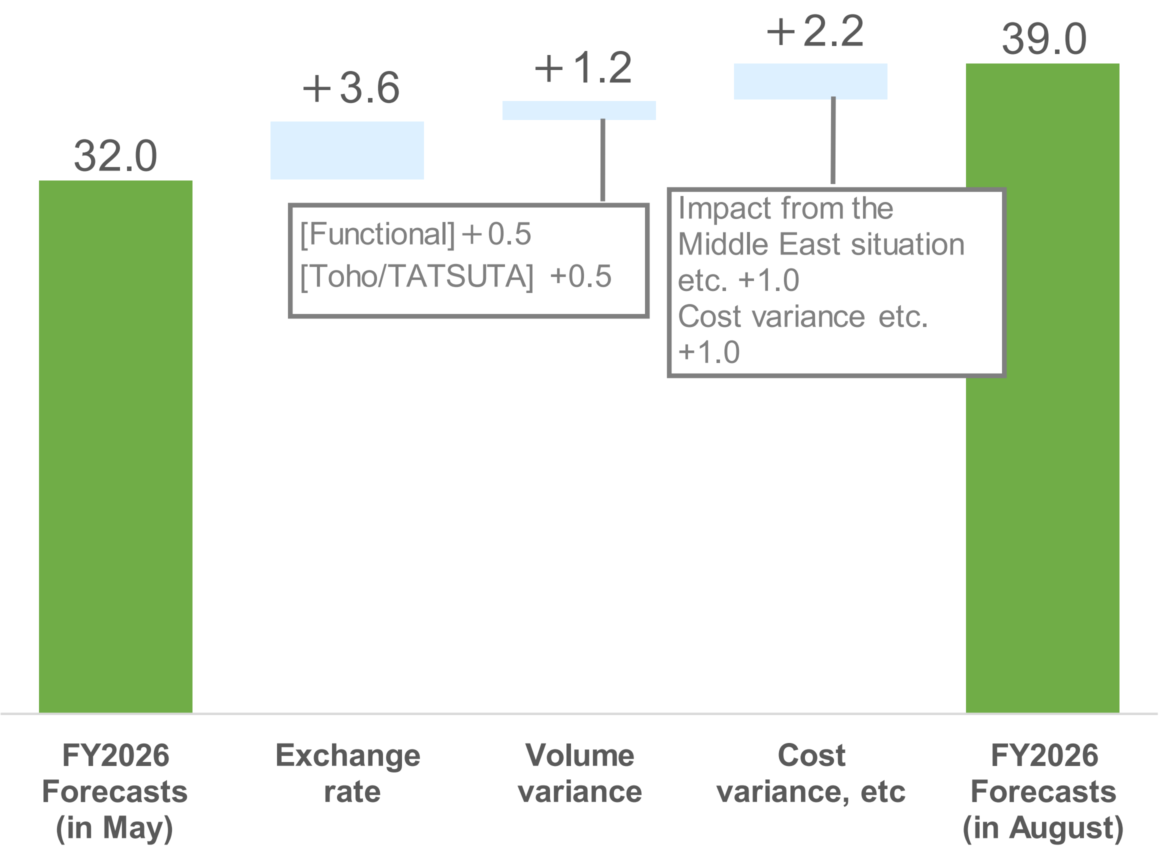
Revenue and operating profit by segment

	bil. yen	FY2026 Forecasts (in May)	FY2026 Forecasts (in August)	Difference Absolute	%
Thin film materials	Revenue	170.0	190.0	+20.0	+12%
	OP	49.0	58.0	+9.0	+18%
Tantalum and Niobium	Revenue	50.0	55.0	+5.0	+10%
	OP	1.0	3.0	+2.0	+200%
Adjustments, etc.	Revenue	- 20.0	- 15.0	+5.0	-
	OP	—	—	-	-
Segment total	**Revenue**	**200.0**	**230.0**	**+30.0**	**+15%**
	OP	**50.0**	**61.0**	**+11.0**	**+22%**

Analysis of difference in operating profit: ICT Materials segment (FY2026 Forecasts: August vs. May Forecasts)

Analysis of difference in operating profit

(bil. yen)



Segment overview

Functional Materials
Toho Titanium, TATSUTA Electric Wire and Cable,

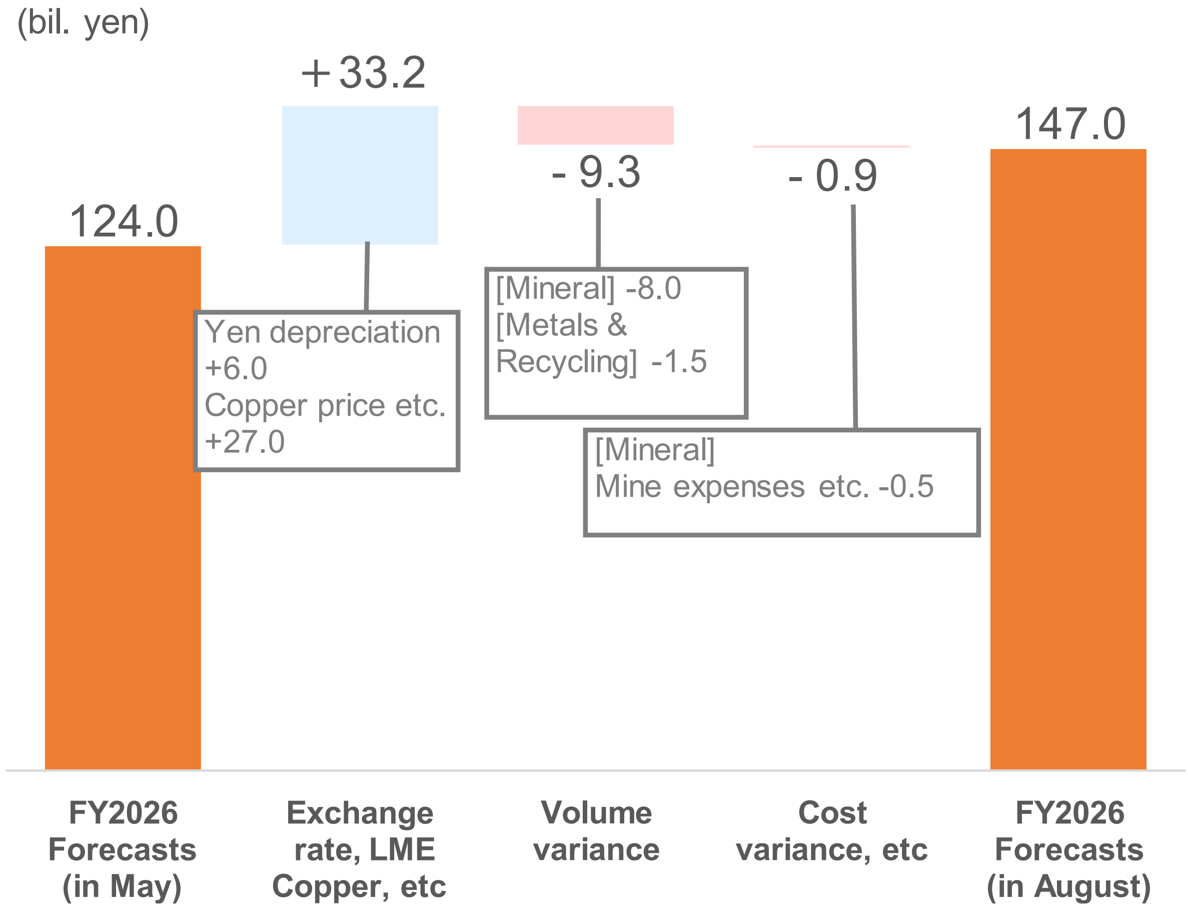
- OP will increase mainly due to yen depreciation and the mitigation of the impact from the Middle East situation

Revenue and operating profit by segment

	bil. yen	FY2026 Forecasts (in May)	FY2026 Forecasts (in August)	Difference Absolute	%
Functional materials	Revenue	160.0	180.0	+20.0	+13%
	OP	23.0	26.0	+3.0	+13%
Toho Titanium, TATSUTAElectric Wire and Cable, and etc.	Revenue	170.0	175.0	+5.0	+3%
	OP	9.0	13.0	+4.0	+44%
Segment total	**Revenue**	**330.0**	**355.0**	**+25.0**	**+8%**
	OP	**32.0**	**39.0**	**+7.0**	**+22%**

Analysis of difference in operating profit: Metals & Recycling segment (FY2026 Forecasts: August vs. May Forecasts)

Analysis of difference in operating profit



Segment overview

Mineral resources
- Despite the reduced mine production due to adverse weather conditions in Chile, OP will increase mainly due to yen depreciation and higher copper price assumption

Metals & Recycling
- OP will increase mainly due to yen depreciation and higher copper price assumption

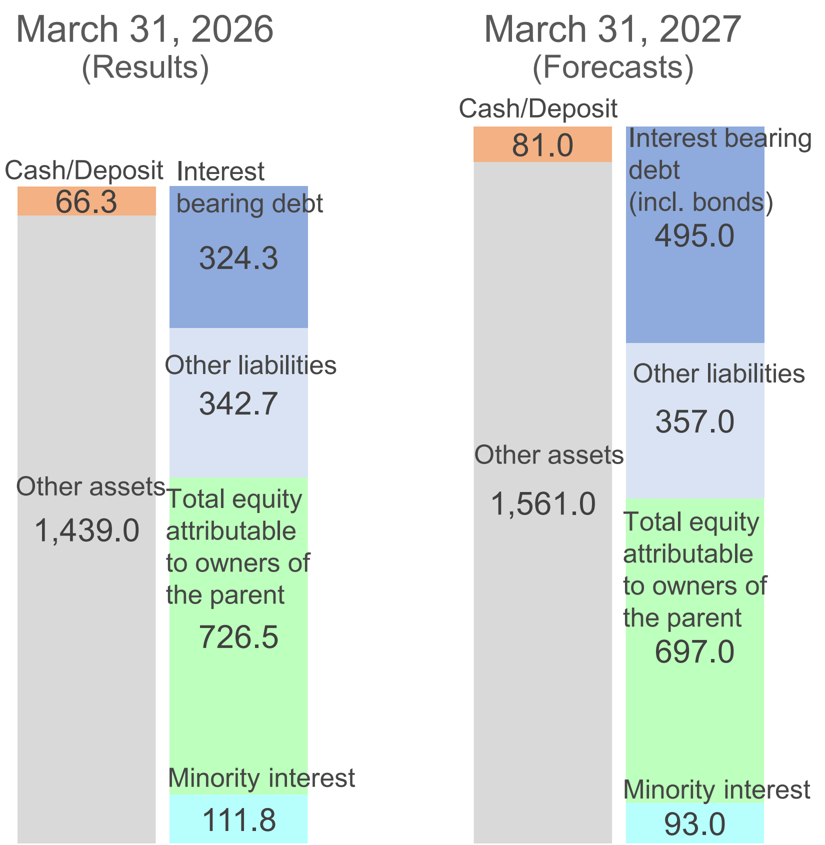
Revenue and operating profit by segment

	bil. yen	FY2026 Forecasts (in May)	FY2026 Forecasts (in August)	Difference Absolute	Difference %
Mineral resources	Revenue	10.0	5.0	- 5.0	- 50%
	OP	97.0	118.0	＋21.0	＋22%
Metals & Recycling	Revenue	410.0	465.0	＋55.0	＋13%
	OP	27.0	29.0	＋2.0	＋7%
Adjustments, etc.	Revenue	—	—	-	-
	OP	—	—	-	-
Segment total	**Revenue**	**420.0**	**470.0**	**＋50.0**	**＋12%**
	OP	**124.0**	**147.0**	**＋23.0**	**＋19%**

Consolidated balance sheet / Cash flows for FY2025, Shareholder returns

Consolidated balance sheet

(bil. yen)



	March 31, 2026	March 31, 2027
Net interest-bearing debt	257.9	414.0

While interest bearing debt is expected to increase mainly due to the issuance of CB, equity will decline thanks to share repurchases, resulting in an improvement in capital efficiency

Consolidated cash flows

(bil.yen)

	FY2026 Forecasts
Cash flows from operating activities	135.0
Cash flows from investing activities	- 95.0
Free Cash Flow	**40.0**
Cash flows from financing activities	- 24.0
Net increase (decrease)in cash and cash equivalents	**16.0**
Impact from exchange rate, etc.	- 1.0

CAPEX

(bil. yen)

Forecasts in May	⇨	Forecasts in August
114.0		135.0

Reflecting capacity expansion investments

Shareholder returns

Dividend Policy (Reproduced)

Our basic dividend policy is to target a consolidated dividend payout ratio of approximately 25% as a benchmark and establish a minimum dividend of ¥20 per share. However, in the event of large-scale asset disposals or share repurchase, we intend to separately consider the total payout ratio. In addition, for the fiscal year ending March 31, 2027, given our execution of a substantial share repurchase (i.e. the Tender Offer), the dividend is expected to be set at the minimum level of ¥20 per share

	FY2026	
	Expected	
Dividend per Share	20 yen	
	Interim	Year-end
	10 yen	10 yen
Dividend payout ratio	13%	

(Reference: Total payout ratio for FY2026 is expected to be approx. 151%)

*Share repurchase amount 194.9 billion yen

Appendix

- Topics - FY2026 (Fiscal year ending March 31, 2027)
- JX Advanced Metals at a Glance
- Company history and the vision to which we aspire going forward
- List of main products
- Our data center-related products
- Overview of Semiconductor sputtering targets
- Strengths of our semiconductor targets that enable a global top market share
- InP substrates
- Initiatives in Base Businesses
- Medium- to long-term business target

Topics - FY2026 (Fiscal year ending March 31, 2027)

Semiconductor Materials | ICT Materials | Metals & Recycling

Metals & Recycling	May	Execution of Final Agreement Concerning Integration of Businesses for the Purchase of Copper Concentrates and the Sale of Related Products
Semiconductor Materials	June	Automation Investment in Semiconductor Sputtering Target Processing Line at Nikko Metals Taiwan
Semiconductor Materials	June	Expansion of Production Capacity for Functional Tantalum Powder at TANIOBIS Plant in Thailand
Semiconductor Materials	June	Expansion of Production Capacity for Sputtering Targets for Magnetic Devices Used in Hard Disk Media
Semiconductor Materials	June	Decision on Capital Investment Policy to Significantly Expand InP Substrate Production Capacity
Semiconductor Materials	June	Expansion of Production Capacity for Materials for Semiconductor Inspection Probe Cards (Rhodium Plating Solutions)
Semiconductor Materials	July	Expansion of Processing Capacity for Semiconductor Sputtering Targets at JX Advanced Metals Korea
ICT Materials	August	Expansion of Production Capacity for Liquid Leakage Detection System in Response to Growing Demand from the AI Data Center Market (TATSUTA)

JX Advanced Metals at a Glance

Leading global supplier of advanced materials in semiconductor and ICT industries

Businesses and Main Products

Focus Businesses

Our highly competitive core business with an advanced technological excellence

☆related to AI Server

Semiconductor Materials

Thin film Materials

Sputtering targets for Semiconductors ☆

#1 Approx. 65%[1]

Metals required for nano-scale deposition on semiconductor wafers

Sputtering targets for magnetic devices ☆

Metals required for nano-scale deposition Large Capacity HDD

InP Substrates ☆

Light emitting and receiving elements in optical communications

CdZnTe Substrates

Single crystal substrates used for radiation and infrared sensors

Material for CVD[4]/ALD[5] Precursors

Metal raw materials used to form thin film in CVD/ALD process

TaNb.

Tantalum powder ☆

Metal powders for sputtering targets for SEMI and capacitors

ICT Materials

Functional Materials

Rolled Annealed Copper Foil (RACF)

#1 78%[2]

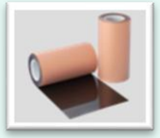
Metal foil with great ductility used for FPC (Flexible printed circuits)[3]

Copper Titanium Alloys ☆

Alloy material with superior strength, conductivity and bendability

TATSUTA

Electromagnetic shielding film



Functional film to protect mobile device circuits from electromagnetic noise

End Uses

AI Servers

Wearable

Smartphones

Mobility (xEV/ADAS)

Base Businesses

Support growth of Focus Businesses by reinforcing sustainable supply chains of copper and minor metals (tantalum, titanium, etc.)

Note 1: Our estimate; Note 2: Fuji Chimera Research Institute, Inc. "Electronics Mounting New Materials Handbook 2024" (actual record in 2023; for FPC only, based on shipping quantity basis); Note 3: FPC (Flexible printed circuits): Electronic circuits with combination of insulated base films and conductive metallic materials made with photolithographic; Note 4: Chemical Vapor Deposition; Note 5: Atomic Layer Deposition

Company history and the vision to which we aspire going forward

Established **Long-term vision**

- Key strategies

Transition from a process industry-type firm to a technology-based firm, aiming to contribute to the realization of a sustainable society as a global leader in the semiconductor and ICT materials sectors to realize a highly profitable structure, even in the face of intensifying international competition

- Target business portfolio

[Growth] Focus Businesses

- *Position as the core of our growth strategy*
- *Aim to achieve profit growth exceeding market growth through technological differentiation*

[Business Foundation] Base Businesses

- *Support growth of Focus Businesses by reinforcing supply chains*
- *Position copper and minor metals indispensable to semiconductor and ICT materials as core domains*

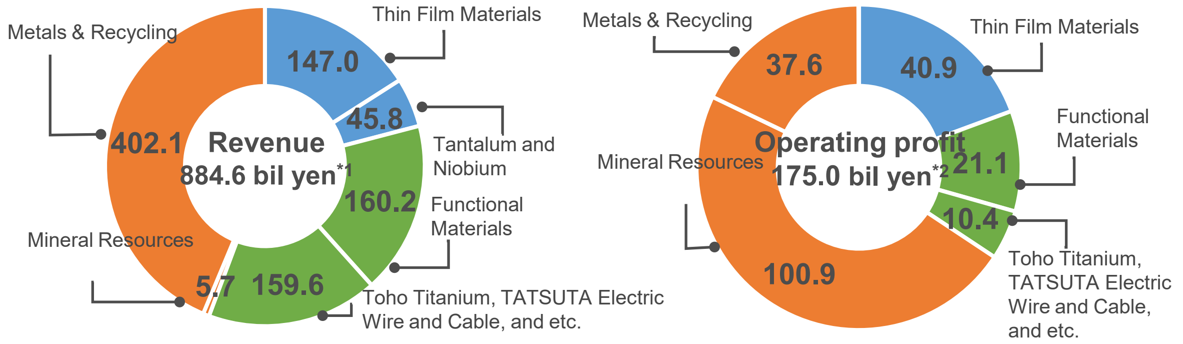
History of the business	Year	Company history
	1905	Founded the Hitachi Mine **(origin of JX Advanced Metals Group)** Foundations of the Nissan Conglomerate, which fostered such companies as Hitachi and Nissan Motor under its umbrella
Expanded into **metal smelting and refining business** Started operations at the Saganoseki Smelter & Refinery	1916	
	1929	Established **Nippon Mining**
Full-scale entry into **metal fabrication business** Established Kurami Works	1964	
Launched **recycling business** Establisehd Hitachi Works Built new recycling furnace	1978	
Full-scale entry into **electronic materials business** Started operations at Isohara Works	1985	
	2002	Established **Nippon Mining Holdings** Established Nippon Mining Holdings (now JX Advanced Metals Corporation) as joint holding company of Nikko Metals and Japan Energy
	2010	**Changed name** to JX Nippon Mining & Metals Corporation Renamed upon the establishment of JXHD (now ENEOS HD) following the merger of Nippon Oil Corporation and Nippon Mining Holdings
	2016	Changed to JX Metals Corporation
Strengthened **minor metals business** Acquired H.C. Starck Tantalum & Niobium (now TANIOBIS GmbH) shares	2018	
Established **Long-term vision**	2019	
Revised long-term vision	2023	
	2024	**Changed** English name English name changed to “JX Advanced Metals Corporation”

JX金属株式会社

List of main products

Main products (photo)

Revenue and operating profit by subsegment (FY2025)

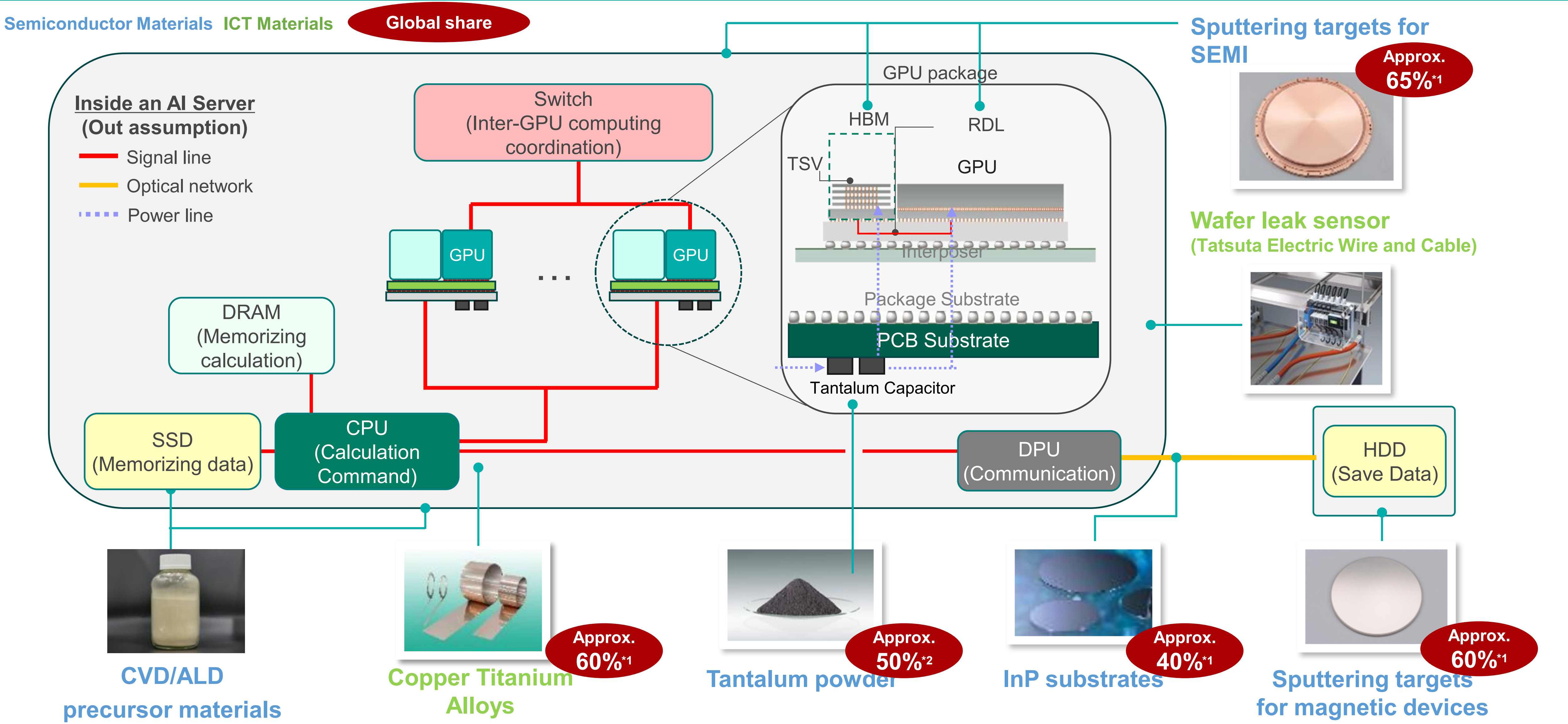


*1: Includes -35.8 billion yen in internal eliminations; 2: Includes common costs, etc. of -35.2 billion yen and Tantalum and Niobium Business operating loss of -0.7 billion yen

As of August 2026

	Segment	Subsegment		Main products	Main applications	End uses
Focus Businesses	**Semiconductor Materials**	Thin Film Materials		Sputtering targets for SEMI	Formation of thin metal film on semiconductor wafers	Semiconductors (data centers, PCs, smartphones)
				Sputtering targets for magnetic devices	Formation of thin metal film on magnetic recording media	HDD (data centers), magnetic sensors
				InP substrates	Optical ⇔ electricity conversion (light-receiving and light-emitting elements)	Optical communication (data centers)
				CdZnTe substrates	Infrared detection, radiation detection	Defense systems, CT scan
				CVD/ALD materials	Wiring materials for semiconductors	Semiconductors (data centers, PCs, smartphones)
		Tantalum and Niobium		Tantalum powder for sputtering targets	Materials for sputtering targets for semiconductors	Semiconductors (data centers, PCs, smartphones)
				Tantalum powder for capacitors	Materials for tantalum capacitors	Tantalum capacitors (data centers, PCs)
	ICT Materials	Functional Materials		Rolled annealed copper foil	Materials for FPC (flexible printed circuits)	Smartphones, wearable devices, robots, medical catheters
				Copper titanium alloys	Connector materials, spring materials for camera modules	Connectors for servers (data centers), camera modules
		Toho Titanium/ TATSUTA Electric Wire and Cable	(Toho Titanium)	Titanium sponge	Aircraft engine parts, fuselage materials	Aircraft, chemical/power plants
				Chemical products (ultra-fine nickel powder)	Materials for internal electrodes of multi-layer ceramic capacitors (MLCC)	Multi-layer ceramic capacitors
				THC catalysts	Catalysts for manufacture of polypropylene, polyolefin	Automotive interiors and exteriors, home appliances, packaging materials
			(TATSUTA)	Wires for infrastructure and industrial equipment	Electric wires	Electric wires and cables for power plants and other plants
				EMI shielding films	Protection for internal circuits of mobile electronic devices	Smartphones
Base Businesses	**Metals & Recycling**	Mineral Resources		Copper concentrate, electrolytic copper, molybdenum concentrate	-	-
				(Ownership interest) Caserones Copper Mine: 25% , Los Pelambres Copper Mine: 12.52%, Escondida Copper Mine: 3%		
		Metals & Recycling		Electrolytic copper, cast copper, precious metals, sulfuric acid	-	-
				(Ownership interest) Pan Pacific Copper: 47.8%		

Our data center-related products



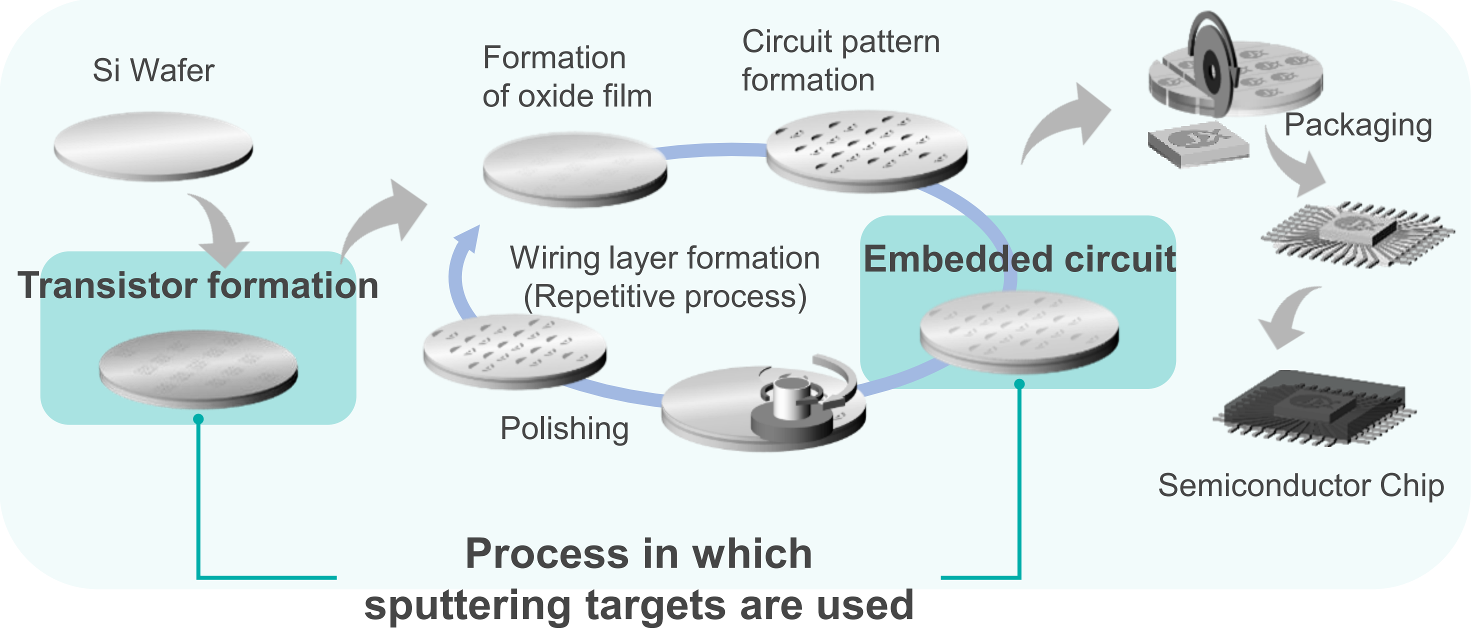
*1 Our estimate; *2 Our estimate, including for sputtering targets ;

Overview of Semiconductor sputtering targets

What is Semiconductor sputtering targets?

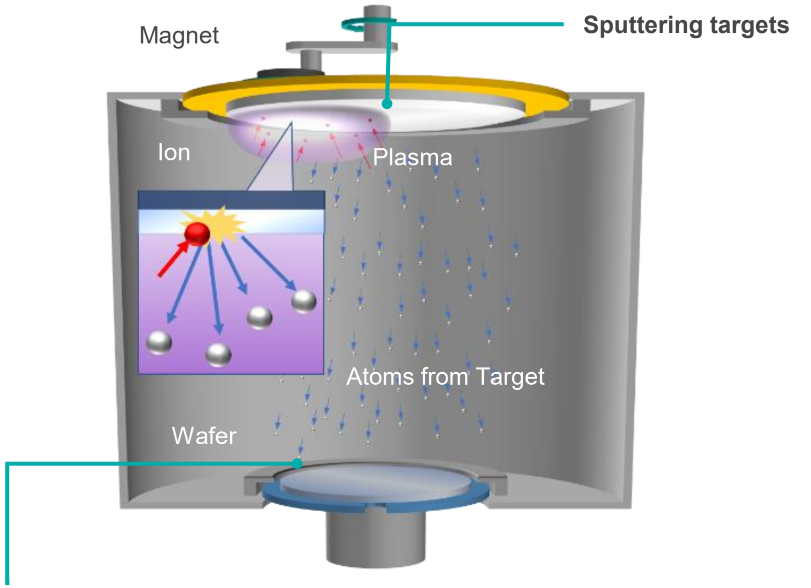
High-purity metal materials required for the PVD*1 process used to form transistors and wiring layers on silicon wafers

Manufacturing Process of Semiconductor Chip

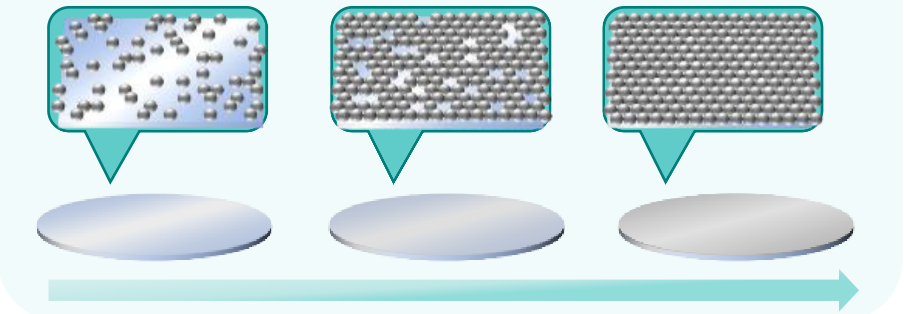


Usage and structure of Semiconductor sputtering targets

Illustrative image of inside sputtering chamber



Film formation in sputtering process (Illustrative)



*1 PVD (Physical Vapor Deposition) : A method in which metal materials are vaporized and deposited onto a substrate. The sputtering method is one of the most common PVD processes.

Strengths of our semiconductor targets that enable a global top market share

Achieving a global top market share through strong technological capabilities, deep relationships with manufacturers and customers, and a fully established global production network

First-class technology

Possess superlative technology such as purification, composition-microstructure control, surface treatment, as well as analysis and evaluation

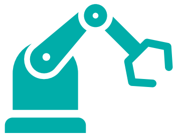
The highest global purity level copper

Purity 99.9999999%

Close-knit partnership with SEMI equipment manufacturers

Designated as the standard materials for SEMI equipment through relationships with SEMI equipment manufactures backed by our development capabilities

JX Advanced Metals



SEMI equipment manufacturer

Long-standing customers (SEMI manufacturers) relationships

Established long-standing suppliance relationships and recognized by SEMI manufactures as a great supplier, exemplified by their awards

TSMC

Intel

SK hynix

Global production network

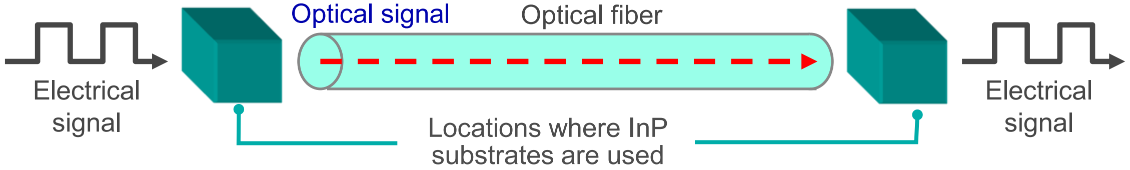
Building a strong global production network that has geographical advantages with SEMI manufacturing

InP substrates

- InP (indium phosphide) substrates for optical communications are seeing **strong sales, driven by data centers**
- The company has decided **to make additional capital investments to expand capacity** to capture demand in this rapidly growing market
- Further **growth potential is expected from the progressive shift to the use of optical communications within data centers**

What are InP substrates?

- Materials used in data centers and internet infrastructure for optical communications where electrical signals are converted into optical signals and vice versa
- Used in the light-receiving and light-emitting elements of optical transceivers

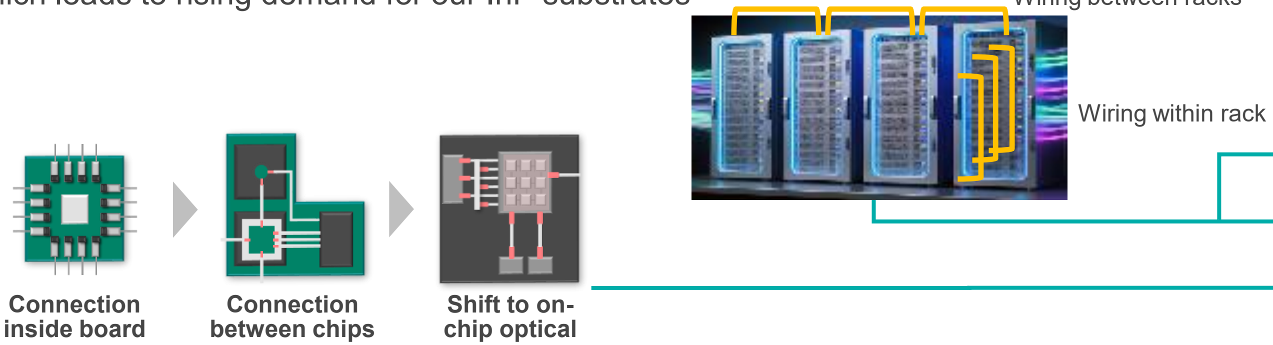


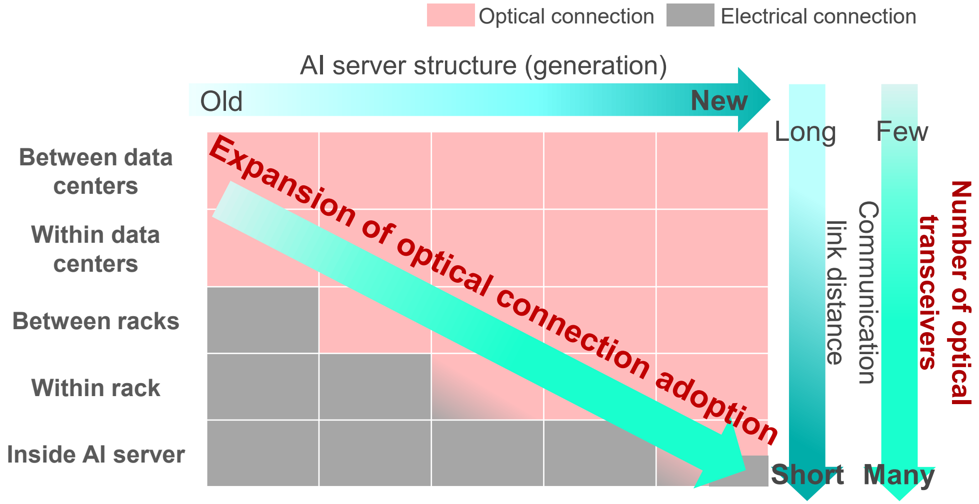
Initiatives to expand InP profitablity

Press release	Production capacity (vs. FY2025)	Investment amount
Jul. 2025	+20%	Approx. 1.5 billion yen
Oct. 2025	Approx. +50%	Approx. 3.3 billion yen
Feb. 2026	Approx. 3x (expected to start operations sequentially from FY2027 onward)	Approx. 20 billion yen
Jun. 2026	Approx. 7-10x	Up to 120 billion yen

Growth opportunities arising from shift from electrical to optical

- With the shift toward higher-speed communications and increasing power consumption within data centers, optical communications are increasingly being applied to shorter distances
- The expanding scope of optical communications is driving higher demand for transceivers, which leads to rising demand for our InP substrates





Initiatives in Base Businesses

Build an optimal Base Businesses structure to advance toward a Focus Businesses centered portfolio aligned with our long-term vision

Key initiatives in Base Businesses: Optimization of business scale and steadily securing the supply chain for focus business

	FY2022	FY2023	FY2024	FY2025	
Mineral Resources *From base metals to minor metals*	Investment in Mibra Mine (Tantalum)	Partial divestment of interests in the Caserones Copper Mine and Los Pelambres Copper Mine	Additional divestment of interests in the Caserones Copper Mine	Participation in Copi PJ (minor metals and rare earth)・Marubeni's participation in the development evaluation	Partial transfer of shares of SCM Minera Lumina Copper Chile, operator of the Caserones Copper Mine, and the transfer of interests in the copper Mine development project in the Frontera Area Acquisition of shares in Fireweed Metals Corp,(minor metals etc.) （Closed in April 2026）
Metals/ Recycling business *Toward a more efficient, recycling-centered structure*	Sale of all shares in LS-Nikko, a copper smelting JV in Korea Acquisition of shares in eCycle (in collaboration with Sojitz)	Partial transfer of shares in Pan Pacific Copper	Enhancing the added value of smelting and recycling businesses (collaborating with Mitsubishi Corporation)	Integration of businesses for the purchase of copper concentrates and the sales of related products by Pan Pacific Copper (JX Advanced Metals, Mitsui Kinzoku, and Marubeni) and Mitsubishi Materials ➢ Execution of Final Agreement The ownership stakes in PPC: JX Advanced Metals 32.50%, Mitsubishi Materials 32.00%, Mitsui Kinzoku 21.90%, Marubeni 13.60%	

Medium- to long-term business target

✓ Steadily progressing toward achieving our goals

		FY2023 Results	FY2024 Results	FY2025 Results	FY2026 Forecasts	(Ref.) CAGR (FY2023-FY2026)	FY2027 Target
Operating profit	[Consolidated]	86.2 bil yen	112.5 bil yen	175.0 bil yen	232.0 bil yen	(39%)	CAGR10%~15% (FY2023-FY2027)
	(Year-on-year growth rate)		30.5%	55.6%	32.6%		
	[Focus Businesses]	27.3 bil yen	51.8 bil yen	71.0 bil yen	100.0 bil yen	(54%)	CAGR35%~40% (FY2023-FY2027)
	(Year-on-year growth rate)		89.7%	37.1%	40.8%		
Operating profit margin	[Consolidated]	5.7%	15.7%	19.8%	22.6%		12%~17%
	[Focus Businesses]	8.8%	12.5%	14.3%	17.1%		15%~20%
	[Semiconductor materials segment]	21.4%	18.0%	22.3%	26.5%		25%~30%
	[ICT materials segment]	0.5%	9.5%	9.9%	11.0%		8%~13%
Percentage of operating profit	[Focus Businesses]	26%	41%	34%	40%		67% or more
	[Semiconductor materials segment]	25%	21%	19%	25%		45% or more
ROE		18.3%	11.0%	15.6%	19.8%		10% or more
Net Debt/EBITDA ratio		2.6x	1.6x	1.2x	1.5x		Less than 1.5x

Disclaimer

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